



Nanotechnology for Novel Nanojoining and Microjoining

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Message from the Guest Editors

Dear Colleagues,

Fast-growing demands on component and product performance and functionality, as well as the trend of continuous miniaturization, require new integral manufacturing solutions. New joining materials combined with innovative low-temperature, pressureless, residue-free joining processes with improved alignment accuracies are needed to overcome the limitations of current bonding and packaging technologies. As a result, the scientific discipline of micro-/nanojoining has recently emerged. Nanojoining is expected to become a key technology for the large-scale production and commercial application of nano-devices and nano-systems in the near-future. Microjoining involves the advanced manufacturing of micro-scaled devices and components. The field of nanojoining focuses on the creation of functional bonds at the nano- or atomic-scale as well as with the utilization of nanoeffects for the development of new joining materials and processes.

This Special Issue is devoted to all scientific and technological aspects related to the emerging field of micro-/nanojoining.





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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal *Applied Sciences* has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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